# Am93L415/Am93L425

1024 x 1 Bit TTL Bipolar IMOX™ RAM

#### DISTINCTIVE CHARACTERISTICS

- Fully decoded 1024-word x 1-bit RAMs
- 93L415A/425A has a 35 ns maximum access time, 65 mA Icc
- Internal ECL circuitry for optimum speed/power performance over voltage and temperature
- Output preconditioned during write to eliminate write recovery glitch
- Available with three-state outputs (Am93L425 series) or with open-collector outputs (Am93L415 series)
- Plug-in replacement for Fairchild 93L415A/415 and 93L425A/425, and Intel 2115/2125 series

#### GENERAL DESCRIPTION

The Am93L415 and Am93L425 are fully decoded 1024 x 1 RAMs built with Schottky diode clamped transistors in conjunction with internal ECL circuitry. They are ideal for use in high-speed control and buffer memory applications. Easy memory expansion is provided by an active LOW chip select input (CS) and either open-collector (93L415) or three-state (93L425) output. Chip selection for large memory systems can be controlled by active LOW output decoders such as the Am74S138.

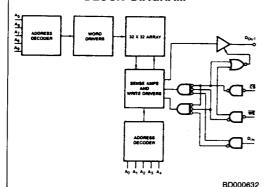
An active LOW write line  $(\overline{WE})$  controls the writing/reading operation of the memory. When the chip select  $(\overline{CS})$  and write lines  $(\overline{WE})$  are LOW, the information on the data input

(D<sub>IN</sub>) is written into the addressed memory word and the output circuitry preconditioned so that true data is present at the output when the write cycle is complete. This preconditioning operation insures minimum write recovery times by eliminating the "write recovery glitch."

Reading is performed with the chip select line LOW and the write line HIGH. The information stored in the addressed word is read out on the noninverting output (D<sub>OUT</sub>).

During the reading and writing operation or any time the chip select line is HIGH, the output of the memory goes to an inactive high-impedance state.

#### **BLOCK DIAGRAM**



### MODE SELECT TABLE

	Inputs	;	Output	
CS	WE	DIN	DOUT	Mode
Н	Х	Х	*Hi-Z	Not Selected
L	L	L	*Hi-Z	Write "0"
L	L	Н	*Hi-Z	Write "1"
L	н	х	Selected Data	Read

H = HIGH L = LOW X = Don't Care

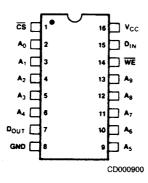
\*Hi-Z implies outputs are disabled or off. This condition is defined as a high-impedance state for the Am93L425 series and as an output high level for the Am93L415 series.

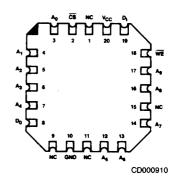
#### PRODUCT SELECTOR GUIDE

Access Time	35 ns	40 ns	45 ns	55 ns	60 ns
Temperature Range	С	М	С	м	С
Open-Collector	Am93L415SA	Am93L415SA	Am93L415A	Am93L415A	Am93L415
Three-State	Am93L425SA	Am93L425SA	Am93L425A	Am93L425A	Am93L425

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# CONNECTION DIAGRAMS Top View



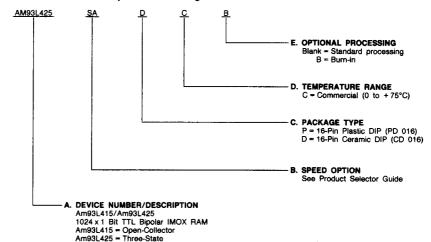


## **ORDERING INFORMATION (Cont'd.)**

#### Standard Products

AMD standard products are available in several packages and operating ranges. The order number (Valid Combination) is formed by a combination of: **A. Device Number** 

- B. Speed Option (if applicable)
- C. Package Type
- D. Temperature Range
- E. Optional Processing



Valid Combinations							
AM93L415SA							
AM93L425SA							
VAM93L415A	PC, PCB,						
AM93L425A	DC, DCB						
AM93L415							
AM93L425							

## Valid Combinations

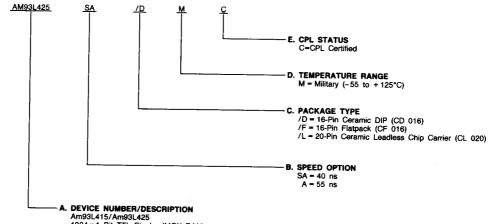
Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations, to check on newly released combinations, and to obtain additional data on AMD's standard military grade products.

## **ORDERING INFORMATION**

#### **CPL Products**

AMD products for Aerospace and Defense applications are available in several packages and operating ranges. APL (Approved Products List) products are fully compliant with MIL-STD-883C requirements. CPL (Controlled Products List) products are processed in accordance with MIL-STD-883C, but are inherently non-compliant because of package, solderability, or surface treatment exceptions to those specifications. The order number (Valid Combination) for APL products is formed by a combination of: A. Device Number

- B. Speed Option (if applicable)
- C. Package Type
- D. Temperature Range
- E. CPL Status



Am93L415/Am93L425 1024 x 1 Bit TTL Bipolar IMOX RAM Am93L415 = Open-Collector Am93L425 = Three-State

Valid (	Valid Combinations						
AM93L425SA	/D140						
AM93L415SA	/DMC,						
AM93L425A	/FMC, /LMC						
AM93L415A	7 /LMC						

#### Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations or to check for newly released valid combinations.

#### ABSOLUTE MAXIMUM RATINGS

Storage Temperature65 to +150°C Ambient Temperature with
Power Applied55 to +125°C
Supply Voltage0.5 V to +7.0 V
DC Voltage Applied to Outputs0.5 V to +V <sub>CC</sub> Max.
DC Input Voltage0.5 V to +5.5 V

Stresses above those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to absolute maximum ratings for extended periods may affect device reliability.

DC Input Current ...... -30 mA to +5 mA

#### **OPERATING RANGES** (Note 6)

Commercial (C) Devices	
Temperature	0 to +75°C
Supply Voltage	+4.75 V to +5.25 V
Military (M) Devices	
Temperature	55 to +125°C
Supply Voltage	+4.5 V to +5.5 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

### DC CHARACTERISTICS over operating range unless otherwise specified\*

Parameter Symbol			onditions	Min.	Typ. (Note 1)	Max.	Units
V <sub>OH</sub> (Note 2)	Output HIGH Voltage	V <sub>CC</sub> = Min. V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OH</sub> = -5.2 mA		3.4		Volts
Vol	Output LOW Voltage	V <sub>CC</sub> = Min., V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OL</sub> = 16 mA		0.33	0.45	Volts
ViH	Input HIGH Level (Note 3)	Guaranteed input logical HI	GH voltage for all inputs	2.1			Volts
ViL	Input LOW Level (Note 3)	Guaranteed input logical LO	W voltage for all inputs			0.8	Volts
l <sub>IL</sub>	Input LOW Current	V <sub>CC</sub> = Max., V <sub>IN</sub> = 0.40 V	V <sub>CC</sub> = Max., V <sub>IN</sub> = 0.40 V			-300	μА
Чн	Input HIGH Current	V <sub>CC</sub> = Max., V <sub>IN</sub> = 4.5 V		1	40	μА	
I <sub>SC</sub> (Note 2)	Output Short Circuit Current	V <sub>CC</sub> = Max., V <sub>OUT</sub> = 0.0 V (Note 5)				-100	mA
loo	Power Supply Current	All inputs = GND	Commercial			65	mA .
lcc	Power Supply Current	V <sub>CC</sub> = Max.	Military			75	
V <sub>CL</sub>	Input Clamp Voltage	V <sub>CC</sub> = Min., I <sub>IN</sub> = -10 mA			-0.850	-1.5	Volts
		CS = V <sub>IH</sub> or WE = V <sub>II</sub>	Am93L415 Series Only		0	100	
1	Output Leakage Current	V <sub>OUT</sub> = 2.4 V	Am93L425 Series Only		0	50	μΑ
ICEX	Output Leakage Current	CS = V <sub>IH</sub> or WE = V <sub>IL</sub> V <sub>OUT</sub> = 0.5 V, V <sub>CC</sub> = Max.	Am93L425 Series Only	-50	0		,
CiN	Input Pin Capacitance	See Note 4			8		pF
Cout	Output Pin Capacitance	See Note 4	See Note 4		10		pF

Notes: 1. Typical limits are at V<sub>CC</sub> = 5.0 V and T<sub>A</sub> = 25°C.

2. This applies only to devices with three-state output. (Am93L425 series)

These are absolute voltages with respect to device ground pin and include all overshoots due to system and/or tester noise.Do not attempt to test these values without suitable equipment.

4. Input and output capacitance measured on a sample basis using pulse technique.

5. Duration of the short circuit should not be more than one second.

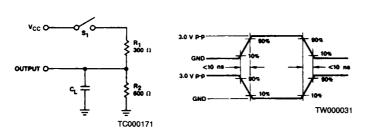
6. Operating specification with adequate time for temperature stabilization and transverse air flow exceeding 400 linear feet per minute. Conformance testing performed instantaneously where T<sub>A</sub> = T<sub>C</sub> = T<sub>J</sub>.
θ<sub>J</sub>A ≈ 60°9w (with moving air) for Ceramic DIP.
θ<sub>J</sub>C ≈ 10 – 17°9w for Flatpack.

<sup>\*</sup>See the last page of this spec for Group A Subgroup Testing information.

# SWITCHING TEST **CIRCUIT**

# **SWITCHING TEST WAVEFORM**

# **KEY TO SWITCHING WAVEFORMS**



WAVEFORM	INPUTS	OUTPUTS
	MUST BE STEADY	WILL BE STEADY
	MAY CHANGE FROM H TO L	WILL BE CHANGING FROM H TO L
	MAY CHANGE FROM L TO H	WILL BE CHANGING FROM L TO H
<b>XXXX</b>	DON'T CARE; ANY CHANGE PERMITTED	CHANGING; STATE UNKNOWN
<del>}}</del> -{{{}	DOES NOT	CENTER LINE IS HIGH IMPEDANCE "OFF" STATE
		V8000010

KS000010

## SWITCHING CHARACTERISTICS over operating range unless otherwise specified\*

			Am93	L415SA	-Am93L	.425\$A	Am93L415A-Am93L425A					8L415/ 3L425	
	Parameter No. Symbol		CO	COM'L MIL		IIL	COM'L		MIL.		COM'L		
No.		Parameter Description	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Units
1	t <sub>PLH</sub> (A)	Delay from Address to Output		35		40		45		55		60	ns
2	t <sub>PHL</sub> (A)	(Note 1)						"		33		00	113
3	tpzH(CS)	Delay from Chip Select to Active		25		40		30	1	45		40	ns
4	tpZL(CS)	Output (Notes 2 and 3)				40	Ī	50		43		40	115
5	t <sub>PZH</sub> (WE)	Delay from Write Enable to											
6	tpZL(WE)	Active Output (Write Recovery) (Note 2 and 3)		20		30		25		35		45	пѕ
7	t <sub>S</sub> (A)	Setup Time Address (Prior to Initiation of Write)	5		5		5		5		5		ns
8	t <sub>h</sub> (A)	Hold Time Address (After Termination of Write)	5		5		5		5		5		ns
9	t <sub>s</sub> (DI)	Setup Time Data Input (Prior to Initiation of Write)	0		5		0		5		5		ns
10	th(DI)	Hold Time Data Input (After Termination of Write)	5		5		5		5		5		ns
11	t <sub>s</sub> (ĈŜ)	Setup Time Chip Select (Prior to Initiation of Write)	5		5		5		5		5		ns
12	t <sub>h</sub> (ĈŜ)	Hold Time Chip Select (After Termination of Write)	5		5		5		5		5		ns
13	t <sub>pw</sub> (WE)	Write Enable Pulse Width to Insure Write	25		30		30		45	,	45		ns
14	t <sub>PHZ</sub> (CS)	Delay from Chip Select to Inactive		30		35		35		40		40	
15	tpLZ(CS)	Output (Hi-Z) (Notes 2 and 3)		30		35		30		40		40	ns
16	t <sub>PHZ</sub> (WE)	Delay from Write Enable to Inactive		30		35		35					-
17	tpLZ(WE)	Output (Hi-Z) (Notes 2 and 3)		30		35		35		40	ĺ	45	ns

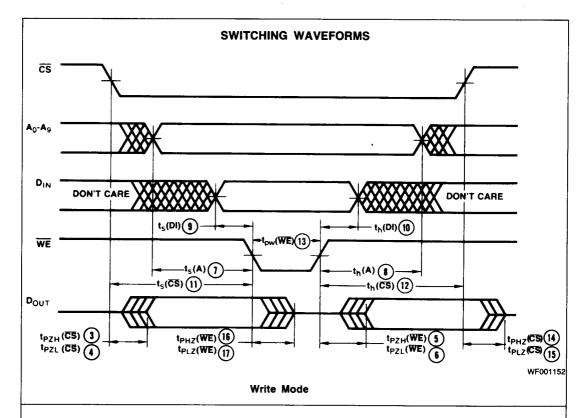
Notes: 1. tpLH(A) and tpHL(A) are tested with S<sub>1</sub> closed and C<sub>L</sub> = 30 pF with both input and output timing referenced to 1.5 V.

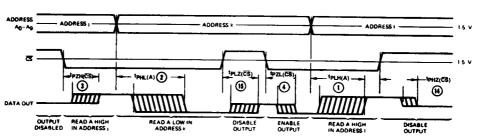
2. For open-collector devices (93L415 series), delays for WE and CS to either an active or inactive output are measured with S<sub>1</sub>

closed and CL = 30 pF; both input and output timing referenced to 1.5 V.

3. For three-state output devices (93L425 series), delays for tp<sub>ZH</sub> and tp<sub>ZL</sub> are measured with C<sub>L</sub> = 30 pF, S<sub>1</sub> open and S<sub>1</sub> closed, respectively. Both input and output timing are referenced to 1.5 V. Delays for tp<sub>HZ</sub> with S<sub>1</sub> open and tp<sub>LZ</sub> with S<sub>1</sub> closed and C<sub>L</sub> ≤ 5 pF are measured between the 1.5 V level on the input and the V<sub>OH</sub> −0.5 V and V<sub>OL</sub> +0.5 V level on the output, respectively.

<sup>\*</sup>See the last page of this spec for Group A Subgroup Testing information.





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#### Read Mode

Switching delays from address and chip select inputs to the data output. For the Am93L425 series, a disabled output is OFF, represented by a single center line. For the Am93L415 series, a disabled output is HIGH.

# GROUP A SUBGROUP TESTING

## DC CHARACTERISTICS

Parameter Symbol	Subgroups
V <sub>OH</sub>	1, 2, 3
V <sub>OL</sub>	1, 2, 3
VIH	1, 2, 3
VIL	1, 2, 3
կլ	1, 2, 3
ин	1, 2, 3
Isc	1, 2, 3
lcc	1, 2, 3
V <sub>CL</sub>	1, 2, 3
ICEX	1, 2, 3

## **SWITCHING CHARACTERISTICS**

No.	Parameter Symbol	Subgroups	No.	Parameter Symbol	Subgroups
1	t <sub>PLH</sub> (A)	9, 10, 11	10	t <sub>h</sub> (DI)	9, 10, 11
2	t <sub>PHL</sub> (A)	9, 10, 11	11	t <sub>s</sub> ( <del>CS</del> )	9, 10, 11
3	t <sub>PZH</sub> ( <del>CS</del> )	9, 10, 11	12	t <sub>h</sub> (CS)	9, 10, 11
4	t <sub>PZL</sub> ( <del>CS</del> )	9, 10, 11	13	t <sub>pw</sub> (WE)	9, 10, 11
5	t <sub>PZH</sub> (WE)	9, 10, 11	14	t <sub>PHZ</sub> (CS)	9, 10, 11
6	t <sub>PZL</sub> (WE)	9, 10, 11	15	t <sub>PLZ</sub> (CS)	9, 10, 11
7	t <sub>S</sub> (A)	9, 10, 11	16	t <sub>PLZ</sub> (WE)	9, 10, 11
8	t <sub>h</sub> (A)	9, 10, 11	17	t <sub>PHZ</sub> (WE)	9, 10, 11
9	t <sub>s</sub> (DI)	9, 10, 11			

#### **MILITARY BURN-IN**

Military burn-in is in accordance with the current revision of MIL-STD-883, Test Method 1015, Conditions A through E. Test conditions are selected at AMD's option.